

Description

The XXW30N15 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.


TO252-2L

General Features

$V_{DS} = 150V$ $I_D = 30A$

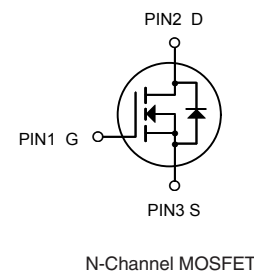
$R_{DS(ON)} < 52m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	150	V
V _{GS}	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current ¹	30	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current ¹	16	A
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current ¹	4.5	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current ¹	3.8	A
IDM	Pulsed Drain Current ²	60	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation ³	72.6	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ³	2.7	W
TSTG	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C
R _{θJA}	Thermal Resistance Junction-ambient ¹	55	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	2.0	°C/W

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	150	165	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=20A$	---	43	52	m Ω
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=10A$	---	45	70	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.8	2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=120V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{DS}=120V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=10A$	---	25	---	S
Q_g	Total Gate Charge	$V_{DS}=75V, V_{GS}=10V, I_D=10A$	---	23	---	nC
Q_{gs}	Gate-Source Charge		---	5.8	---	
Q_{gd}	Gate-Drain Charge		---	4.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=75V, V_{GS}=10V, R_G=3.3\Omega, I_D=10A$	---	16.2	---	ns
T_r	Rise Time		---	18.6	---	
$T_{d(off)}$	Turn-Off Delay Time		---	28.5	---	
T_f	Fall Time		---	6.5	---	
C_{iss}	Input Capacitance	$V_{DS}=75V, V_{GS}=0V, f=1\text{MHz}$	---	1190	---	pF
C_{oss}	Output Capacitance		---	73	---	
C_{rss}	Reverse Transfer Capacitance		---	4	---	
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V, \text{Force Current}$	---	---	20	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=10A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	45	---	nS
Q_{rr}	Reverse Recovery Charge	$T_J=25^{\circ}\text{C}$	---	138	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150 $^{\circ}\text{C}$ junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

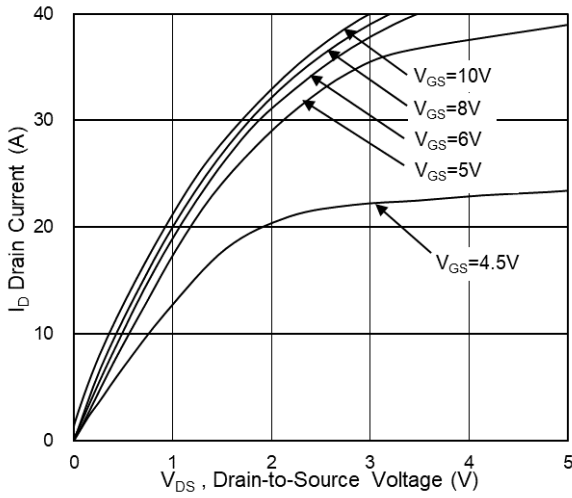


Fig.1 Typical Output Characteristics

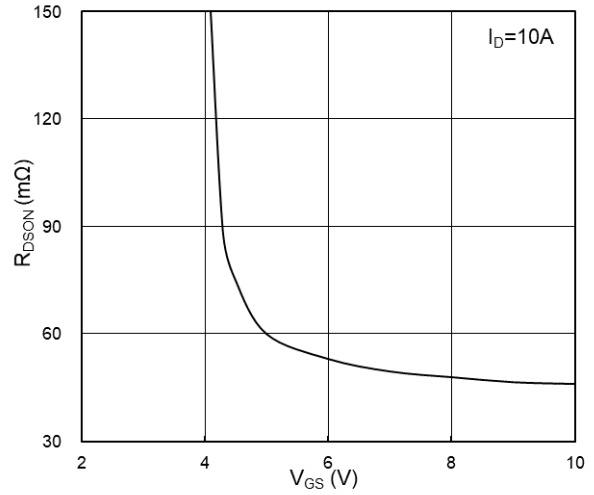


Fig.2 On-Resistance vs G-S Voltage

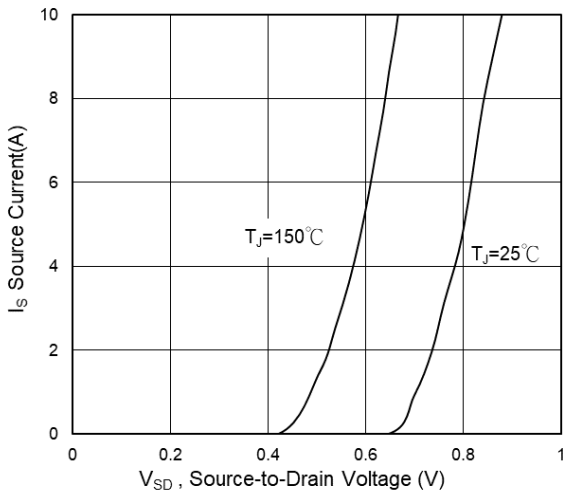


Fig.3 Source Drain Forward Characteristics

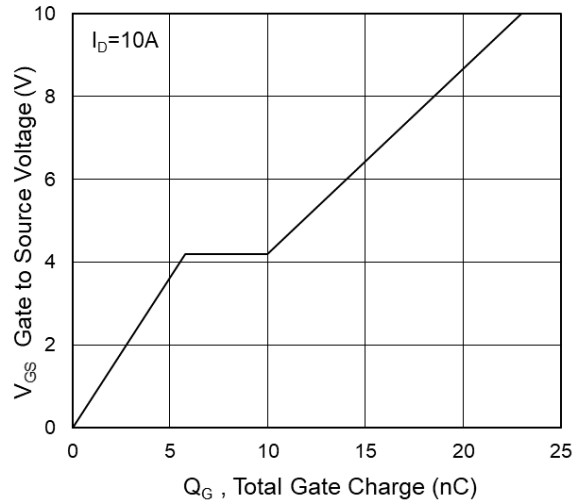


Fig.4 Gate-Charge Characteristics

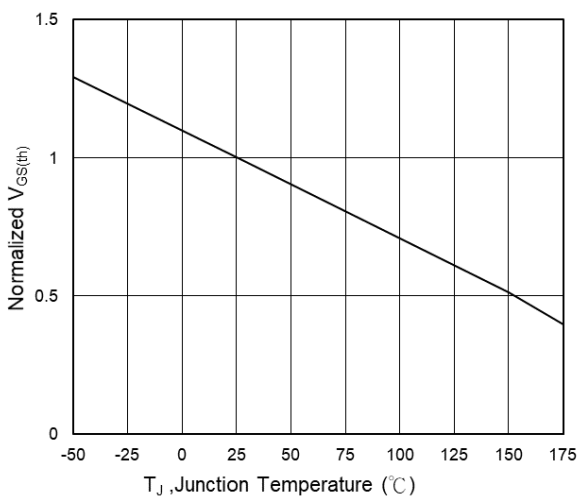


Fig.5 Normalized $V_{GS(th)}$ vs T_J

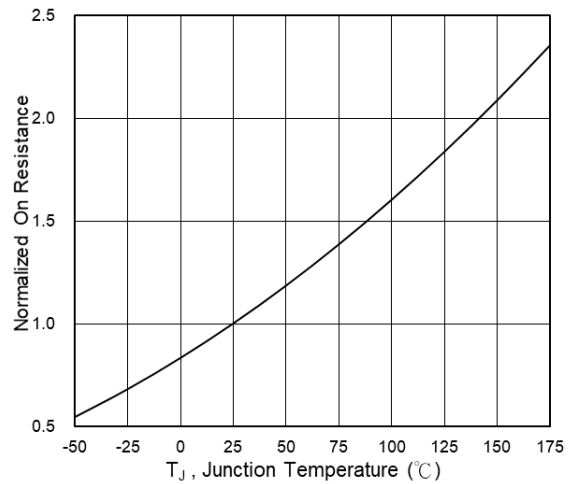


Fig.6 Normalized R_{DSON} vs T_J

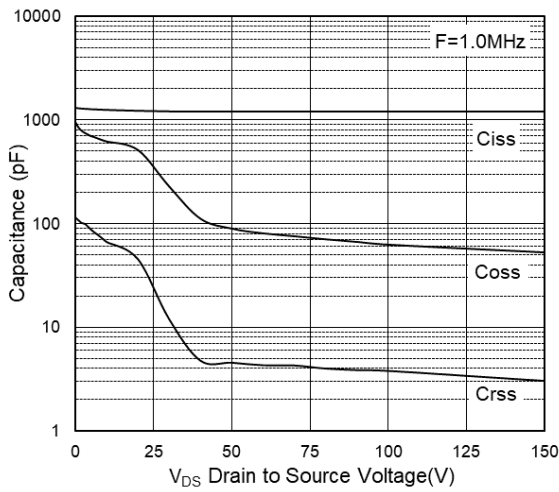


Fig.7 Capacitance

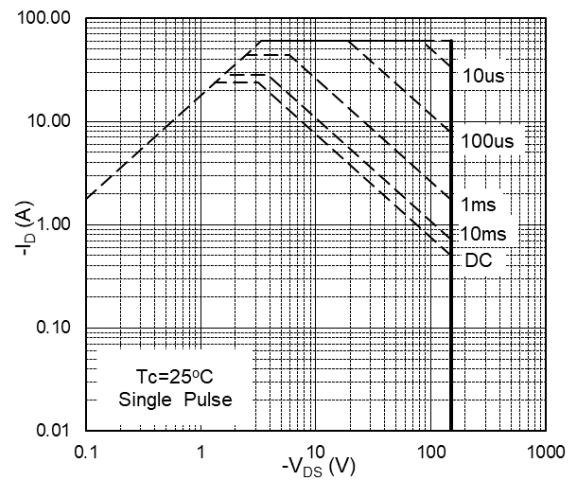


Fig.8 Safe Operating Area

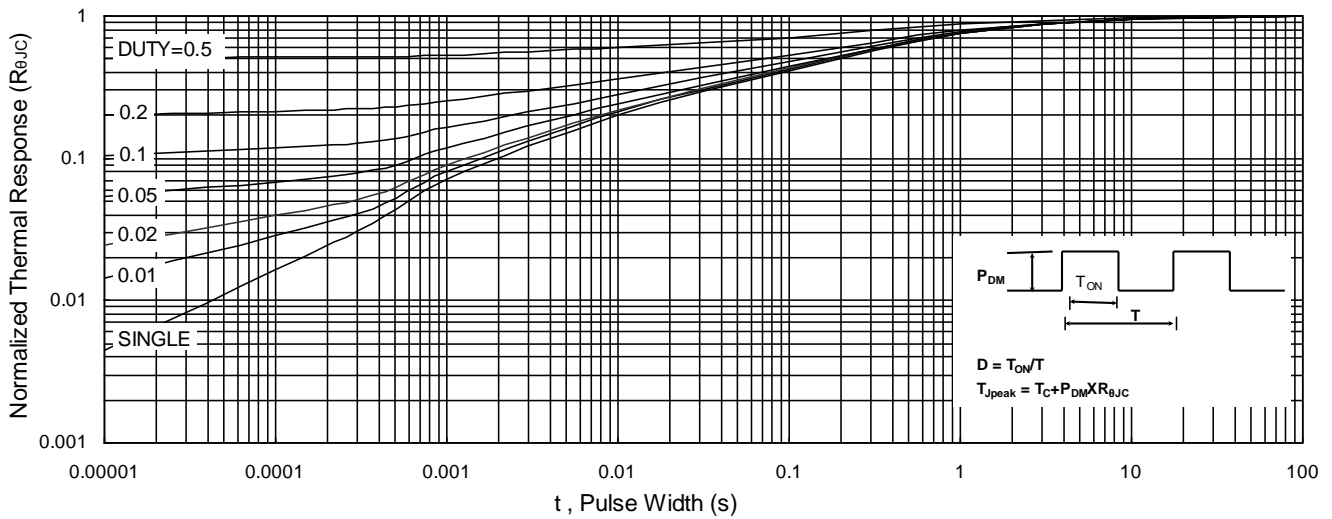


Fig.9 Normalized Maximum Transient Thermal Impedance

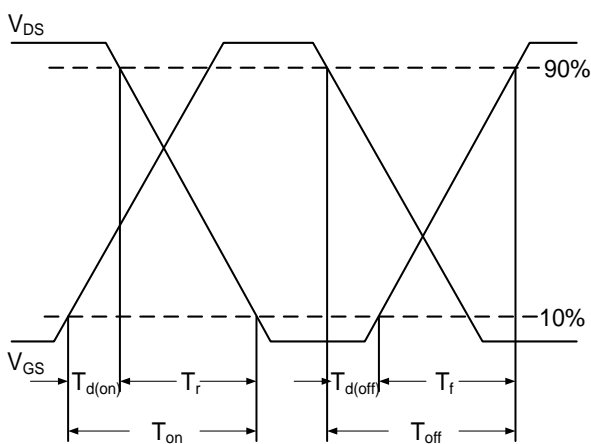


Fig.10 Switching Time Waveform

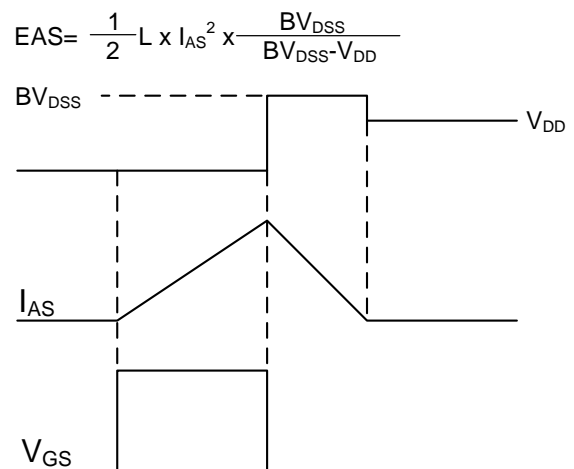


Fig.11 Unclamped Inductive Switching Waveform

